

# UTILITY PATENT APPLICATION

HONORABLE COMMISSIONER OF  
PATENTS AND TRADEMARKS  
Washington D.C. 20231

Docket No.: 3008-28  
Client Ref.: PHNF-01094



06/28/01

Sir:

Transmitted herewith for filing is the patent application of:

INVENTOR(S): Seigi Aoyama, Takaaki Ichikawa, Hiromitsu Kuroda, Takashi Nemoto, Atsushi Ohtake and Hiroyoshi Hiruta  
FOR: LEAD FREE SOLDER, AND CONNECTION LEAD AND ELECTRICAL COMPONENT USING SAID LEAD FREE SOLDER

Enclosed are:

- [X] 24 pages of specification, claims, abstract
- [X] Declaration & Power of Attorney.
- [X] Priority Claimed
- [X] 4 sheets of drawing.
- [X] An assignment of the invention to Hitachi Cable Ltd. and the assignment recordation fee.
- [X] Certified copy of JP Application No. 2001-61650
- [] An associate power of attorney.
- [] Preliminary Amendment
- [X] Information Disclosure Statement, Form PTO-1449 and reference.

The filing fee has been calculated as shown below:

(1) FOR	(2) NO. FILED	(3) NO. EXTRA	(4) RATE	(5) AMOUNT
TOTAL CLAIMS	13	-20	x \$18.00 =	\$ .00
INDEPENDENT CLAIMS	3	-3	x \$80.00 =	.00
MULTIPLE DEPENDENT CLAIM(S) (If applicable)			+ \$ ____ .00 =	00.00
BASIC FEE				\$710.00
Total of above calculations			=	\$710.00
Subtract 1/2 if Small Entity			=	\$ ____ .00
[X] Assignment & Recording Fee				\$40.00
TOTAL FEE				\$750.00